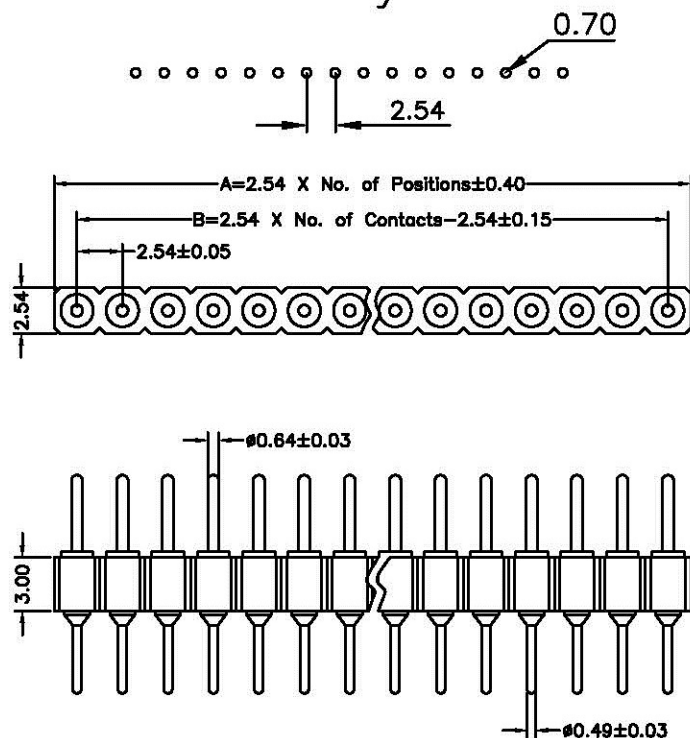


P.C.B. Layout



How To Order

RI- (1) (2) / (3) - (4) / (5)

(1) No. of contact (2) P : Plug S : Socket

(3) 1 : Single Row / 2 : Double Row / 3 : 0.3" Row to Row Pitch /
4 : 0.4" Row to Row Pitch / 6 : 0.6" Row to Row Pitch

(4) Contact Plating

GF : Gold Flash / T200 : Tin 200 μ / SG : Select Gold Flash /

S10 : Select Gold plated 10 μ / S15 : Select Gold plated

15 μ / S30 : Select Gold plated 30 μ

(5) Blanked : Dip Solder Type / W : Wire Wrapping / D : SMD Type

E : Empty , No Bar / R : Right angle

Ex. RI-10PR/1-SG

Plug , For Round IC Socket 10Pin / Single Row , Select Gold Flash /
Right angle

Ex. RI-12S/1-SG

Round IC Socket 12Pin , Socket / Single Row , Select Gold Flash

Technical Data

Material:

Pin(outer sleeve): Brass, machined CuZn38Pb2

Plating(outer sleeve):

Tin plated: 2 μ m/80 μ "Ni, 5 μ m/200 μ "Sn

Gold Plated: 2 μ m/80 μ "Ni, Full gold

Insulator(black): Black (PPS) UL94V-0

Electrical:

Current rating: 3Amps/contact max.

Contact resistance: $\leq 4m\Omega$ /contact

Insulation resistance: $\geq 5000M\Omega$ at V=500V

Dielectric Withstanding Voltage: 1000V AC Min

Operating voltage: 60VAC/DC

Mechanical:

Operating temperatures: Gold Plated: -55 $^{\circ}$ C to +125 $^{\circ}$ C

Tin plated: -40 $^{\circ}$ C to +105 $^{\circ}$ C

Soldering temperature: +260 $^{\circ}$ C, 10s max.

				FLYING			
				TOLERANCES ARE	APPROVED	DATE	DRAWING NO
				X. ± 0.25	AP-ABDXX10XXS		
				X.X ± 0.1	CHECKED	DATE	NAME
				X.XX ± 0.01			
				X.XXX ± 0.005	DRAWN	DATE	UNIT
				X.XXXX ± 0.002	Lee	2006/06/02	MM
							SCALE
							1:1
							REV
							A